

# SPECIFICATION

REFOND P/N

RF-W\*TI32DS-EF-2N

R&D

Mass Product

REFOND

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## 1. Description

### 1.1 General Description

The White LED which was fabricated using a blue chip and the phosphor

Product Package: 2.8mmX3.5mmX0.7mm.

LED

2.8mmX3.5mmX0.7mm

### 1.2 Features

PLCC Package.

Extremely wide viewing angle.





## 1.5 Product Parameters

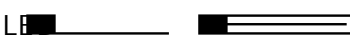
Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	VF	IF=60mA	2.7	2.78	3.0	V
Reverse Current	IR	VR=5V	---	---	10	uA
RF-W4T132DS-EF-2N (3760-4350K)		IF=60mA	24	25.8	28	lm
RF-W5T132DS-EF-2N (4620-5410K)		IF=60mA	24	25.8	28	lm
Viewing Angle	2 1/2	IF=60mA	---	120	---	deg
Color Rendering Index	CRI	IF=60mA	90	91.5	---	---
Electrostatic Discharge	ESD	HBM	2000	---	---	V
Thermal Resistance.	RTHJ-S	IF=60mA	---	---	35	W

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P <sub>D</sub>	540	mW
Forward Current	I <sub>F</sub>	180	mA
Peak Forward Current	I <sub>FP</sub>	300	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>OPR</sub>	-40 ~ +85	
Storage Temperature	T <sub>STG</sub>	-40 ~ +100	
Junction Temperature	T <sub>J</sub>	125	

Notes

1. 1/10 Duty cycle, 0.1ms pulse width.      0.1ms,      1/10.
2. The above forward voltage measurement allowance tolerance is  $\pm 0.1V$ .       $\pm 0.1V$ .
3. The above color coordinates measurement allowance tolerance is  $\pm 0.005$ .       $\pm 0.005$ .
4. The above luminous intensity measurement allowance tolerance  $\pm 10\%$ .       $\pm 10\%$ .
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature. junction temperature should not exceed the maximum rate. 
8. ESD yield is over 90% at 2000V ESD (HBM). ESD protection



### 1.6 Bin Range Of Forward Voltage and Luminous Flux

**BIN**

Table 1-3

VF(V)	F2	G1	G2
	2.7-2.8	2.8-2.9	2.9-3.0
(LM)	QHA	QIA	
	24.0-26.0	26.0-28.0	

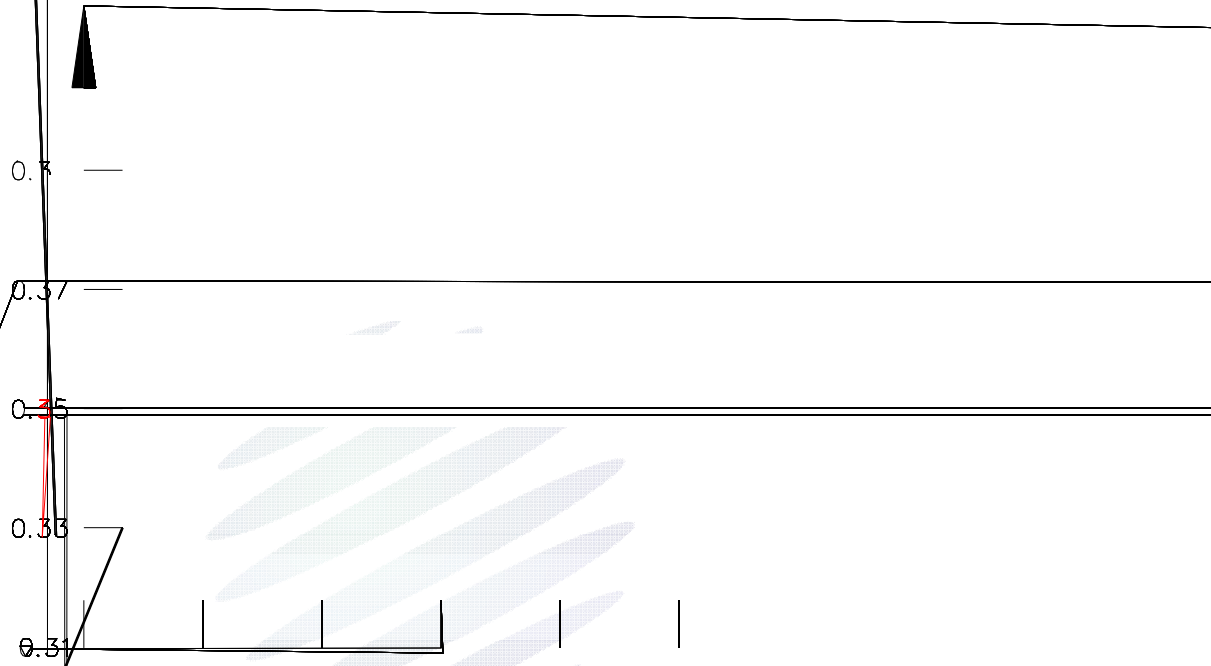


Fig 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	X1	Y1	X2	Y2	X3	Y3	X4	Y4				
E40	0.3871	0.3894	0.3769	0.3838	0.3729	0.3704	0.3832	0.3761				
E50	0.3518	0.3705	0.3408	0.3614	0.3402	0.3475	0.3512	0.3566				
BIN CODE	X1	Y1	X2	Y2	X3	Y3	X4	Y4	X5	Y5	X6	Y6

## 1.7 Typical optical characteristics curves

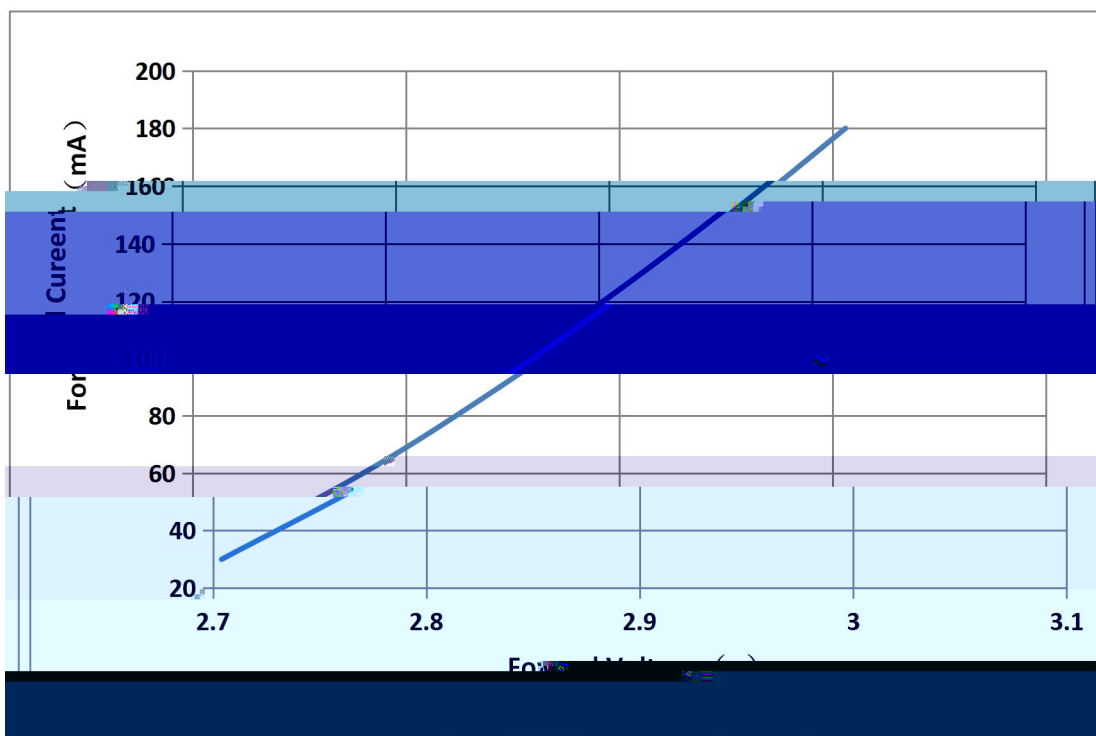


Fig 1-7 Forward Voltage Vs. Forward Current

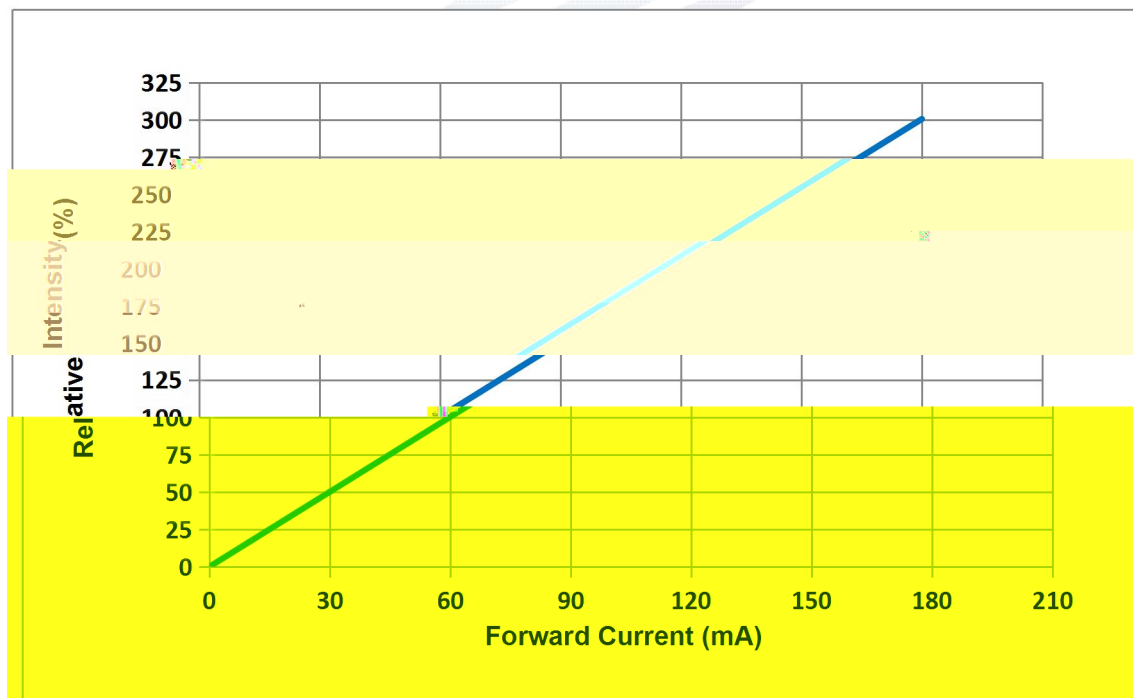


Fig 1-8 Forward Current Vs. Relative Intensity



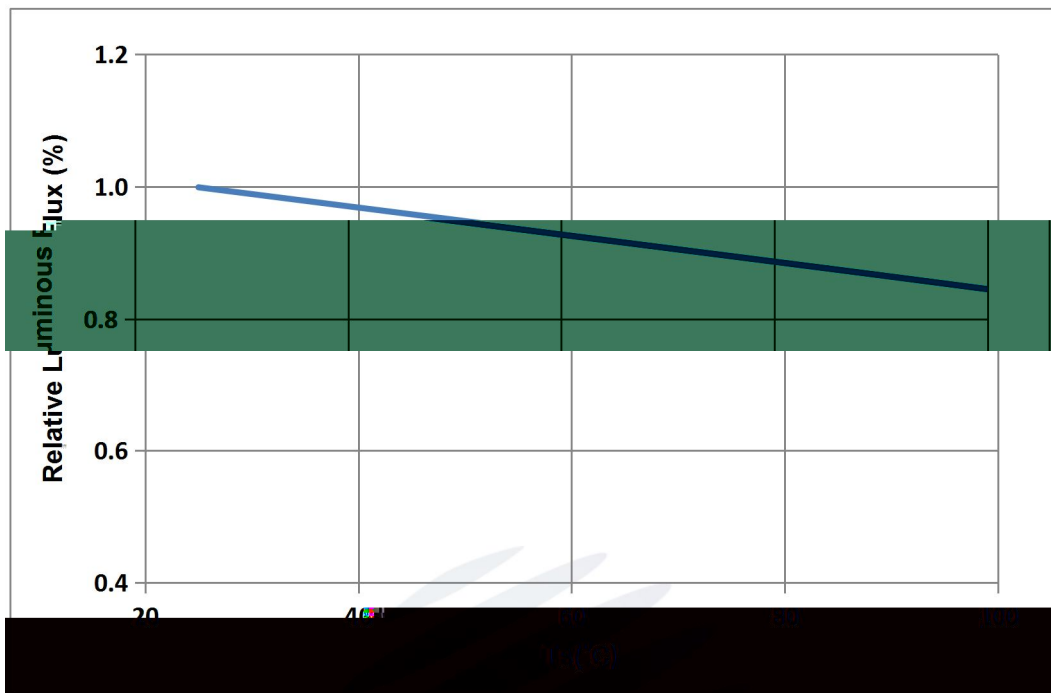


Fig 1-9 Solder Temperature Vs Relative Intensity

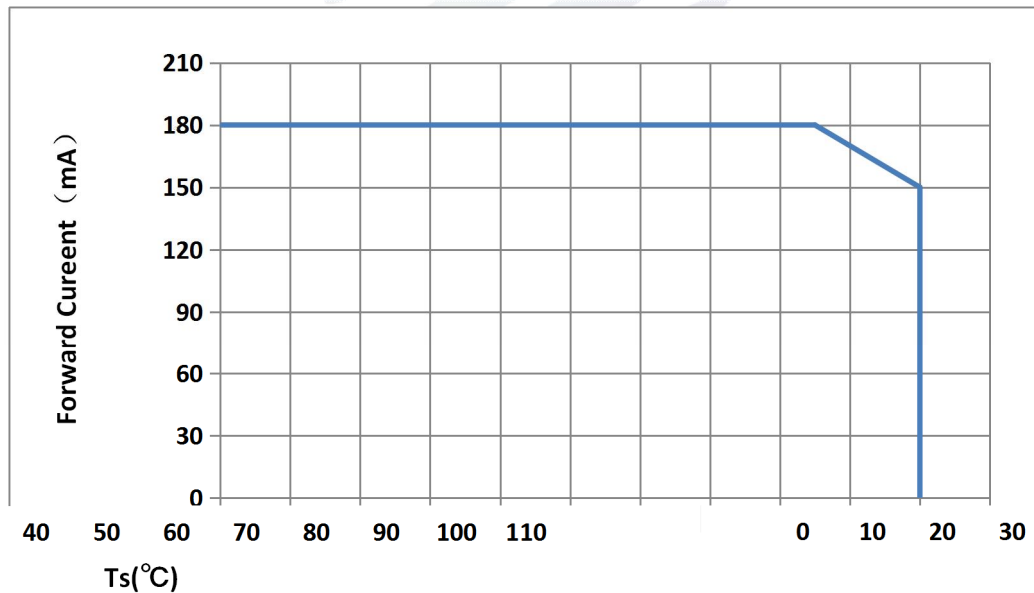


Fig 1-10 Solder Temperature Vs Forward Current

Tj 125

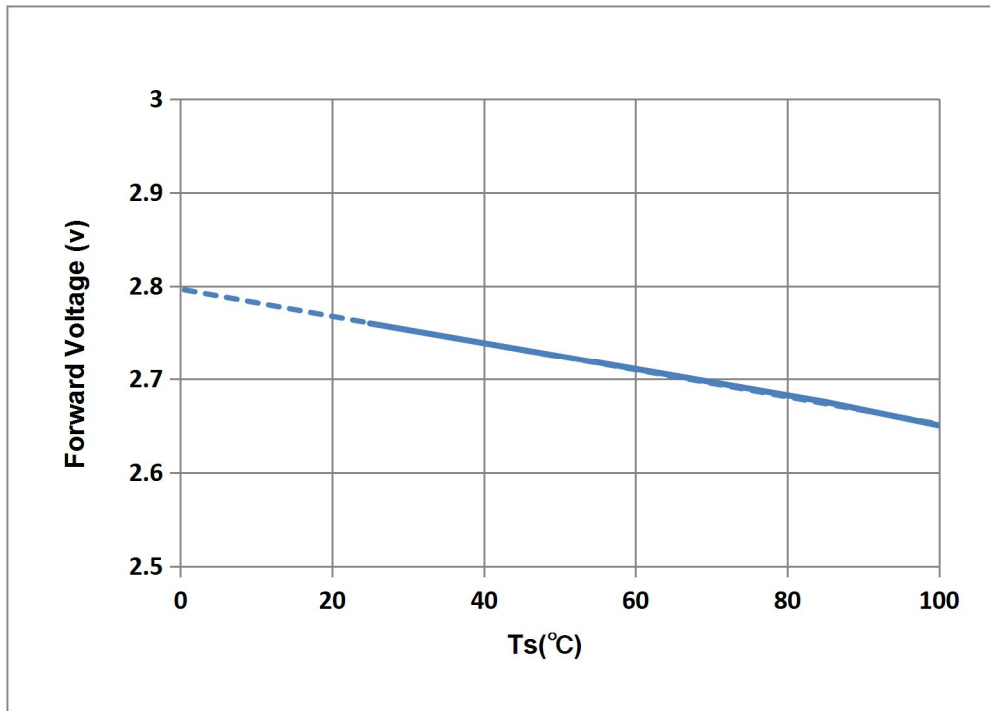


Fig 1-11 Forward Voltage Vs Solder Temperature

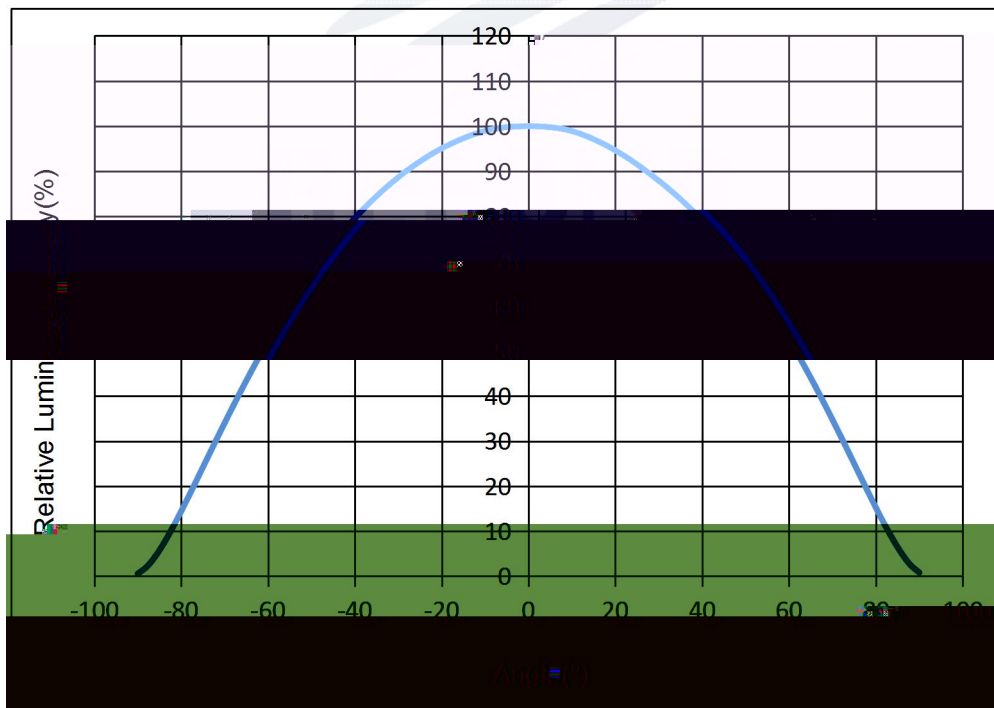


Fig 1-12 Radiation diagram

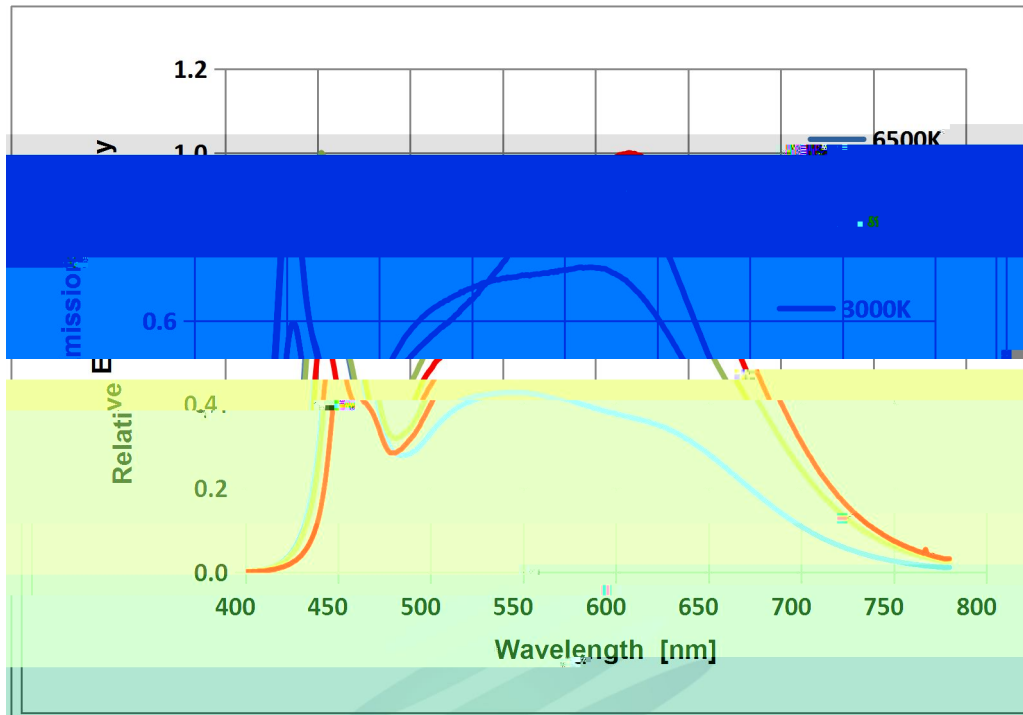


Fig 1-13 Spectrum Distribution

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## 2 . Packaging

### 2.1 Packaging Specification

Package:12000/4000pcs/reel.

#### 2.1.1Carrier Tape Dimension

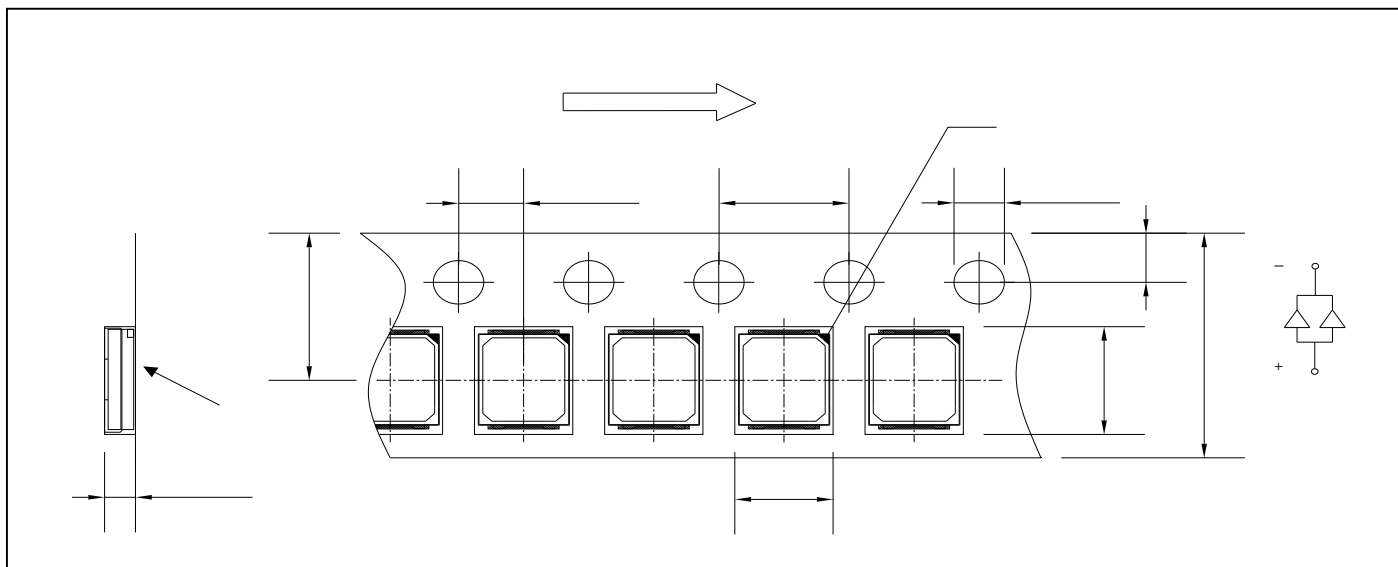


Fig.2-1 Carrier Tape Dimension

#### 2.1.2Reel Dimension

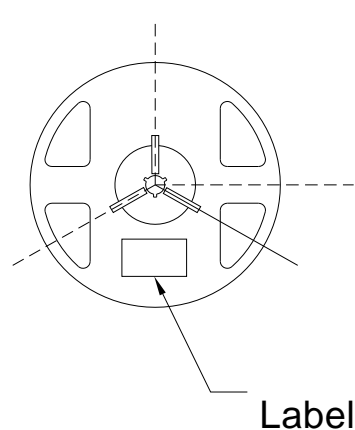


Fig.2-2Title

Table 2-1 Title

A	8.7±0.3mm	A	8.5±0.3mm
B	290±2.0mm	B	178±1.0mm
C	79.6±0.2mm	C	59±1.0mm
D	14.2±0.2mm	D	13.5±0.3mm
12K		4K	

#### Notes

The tolerances unless mentioned  $\pm 0.1$ mm. Unit : mm

$\pm 0.1$

### 2.1.3 Label Form Specification

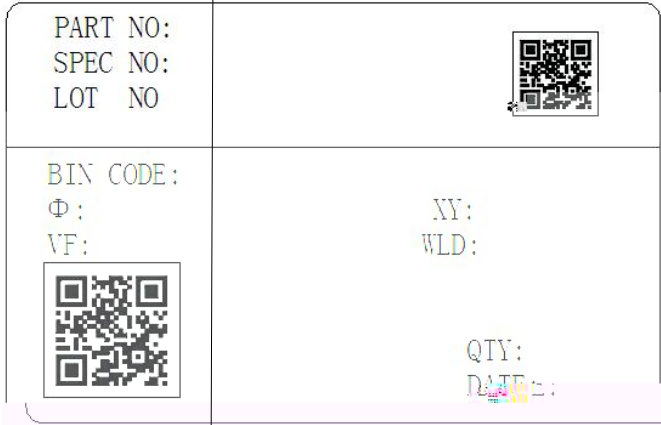


Fig 2-3 Title

Table 2-2 Title

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V <sub>F</sub>	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

### 2.2 Moisture Resistant Packing

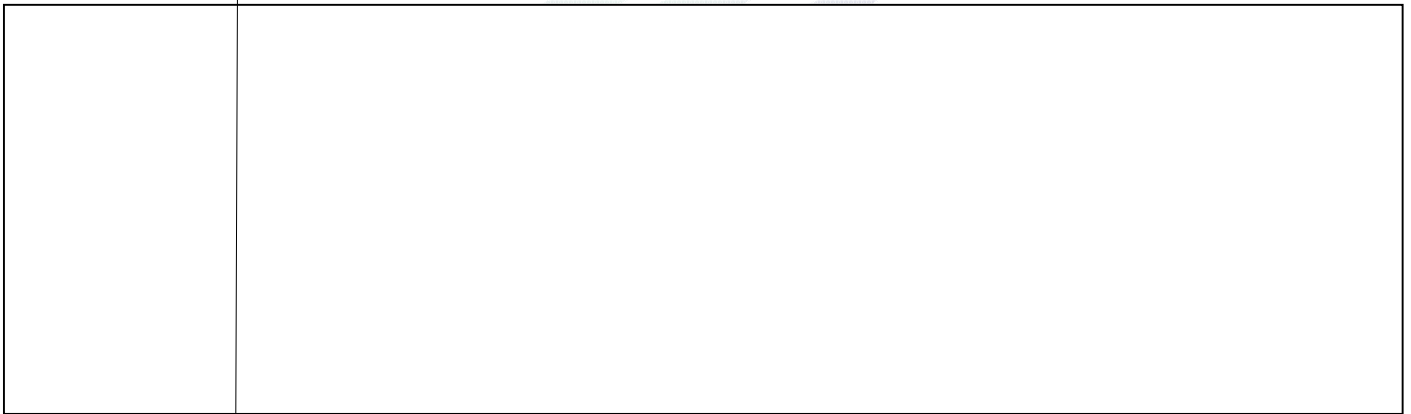
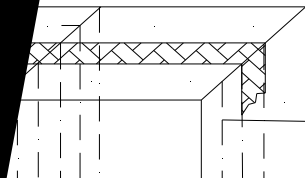


Fig.2- Title

Box





## 2.5 Criteria For Judging Damage

Table 2-4 Title

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	$V_F$	$I_F=60mA$	-	$(6.5 \sim 1.9) \times 10^{-1} V$
Reverse Current				



## SMT Reflow Soldering Instructions SMT

### 3.1 SMT Reflow Soldering Instructions SMT

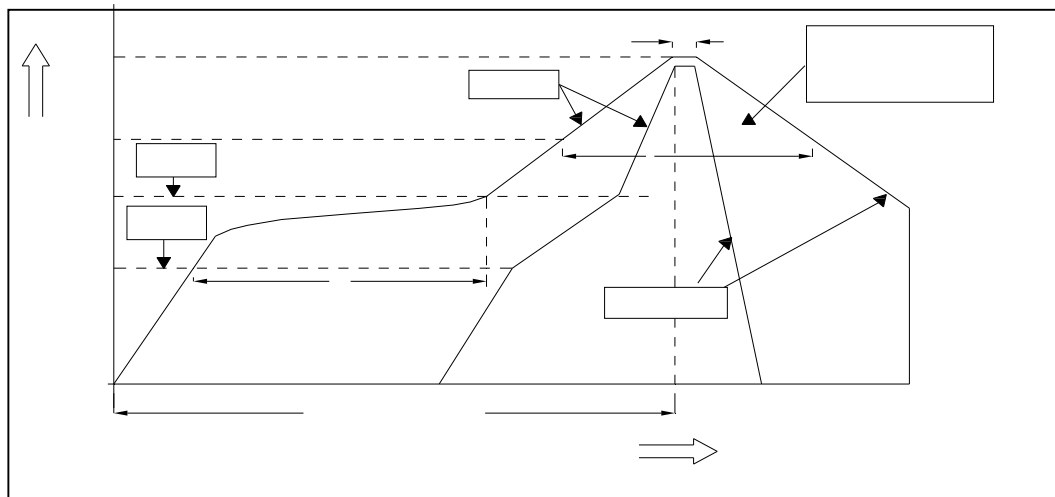


Fig.3-1Title

Table 3-1Title

Average temperature rise speed	$T_{smax}$	$T_P$	3 °C/	Max 3 °C/ s
Preheating: minimum temperature	(T <sub>smin</sub> )		150 °C	
Preheating: Max temperature	(T <sub>smax</sub> )		200 °C	
Preheating: Time	T <sub>smin</sub>	T <sub>smax</sub>	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature	(T <sub>L</sub> )		217 °C	
Time limited to maintain high temperature: The Time	(t <sub>L</sub> )		60	Max 60s
Peak /Classification of temperature:	/	(T <sub>P</sub> )	260 °C	
Time limit classification of peak temperature time	t <sub>p</sub>		10	Max 10s
Hold time within 5 °C with the actual peak temperature (TP)	(T <sub>P</sub> )	5 °C	30	Max 30s
Cooling speed			6 °C/	Max 6 °C/ s
Needed time from 25 °C to T <sub>p</sub>	25 °C		8	Max 8 minutes



## Notes

(1) Reflow soldering should not be done more than two times. Soldering after first, LEDs will be damaged.

### LED

(2) When soldering, do not put stress on the LEDs during heating.

#### 3.1.1 Soldering Iron

(1) When hand soldering, keep the temperature of iron below less 300 less than 300  
300 3

(2) The hand solder should be done only one time.

#### 3.1.2 Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

### LED

### LED

#### 3.1.3 Cautions

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

## Handling Precautions

### 4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

900PPM 900PPM

1500PPM.

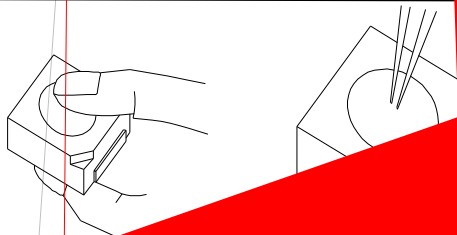
(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED

LED

LED

## LED

(4) Handle the component along the side of the package, do not directly touch or Handle the silicone lens



(5) In designing a circuit, the operating current must be within the rating specified for each LED, otherwise slight voltage fluctuations in the circuit must be designed. When voltage is applied to LED

## LED

(6) Thermal Design is paramount. LED Characteristics decline, such as efficiency, when the heat generation of the LEDs

(7) Compared to standard encapsulation, the silicone lens is more likely to attract dust, requiring special care during assembly. Although dust particles cannot be guaranteed, a special cleaning process is required after the soldering of components. Refond provides a cleaning solution for cleaning. In case

other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

### LED

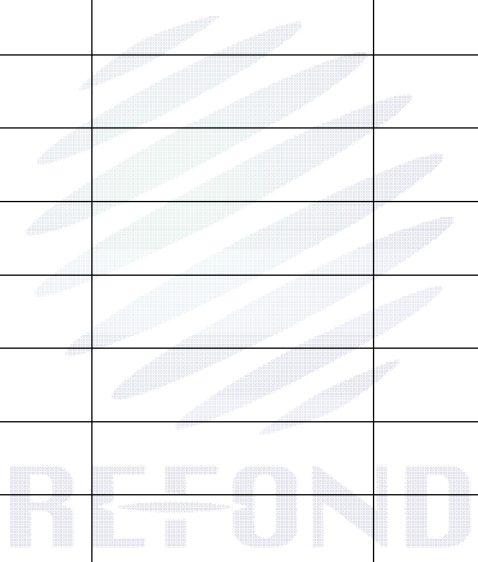
Table 4-1 Storage

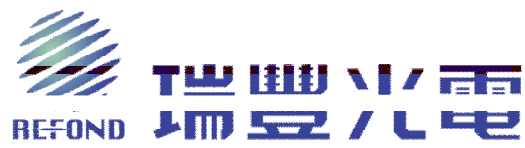
Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60±5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time baking treatment should be performed after unpacking and based on the following condition 60

## Version History/

Date	Revisor	Version	Verifier	Remarks
2021-3-2		E/0		





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Declare

This specification is written both in English and in Chinese and the latter is formal.